UI Science Profile

Equipment for next generation

UI SCIENCE Co.,ltd.

Confidential

Profile of UI SCIENCE

○Head office　UI SCIENCE Co., ltd.

○Address　1059-5 TAKATA KASHIWA City CHIBA JAPAN
TEL 04-7137-7383 FAX 04-7137-7384

○Company Profile

Established	September 2016
Capital	100,000,000Jpy
Maine bank	Chiba bank、Keiyo bank
Representative Director and President	Shinichi Umemoto
Sales results 2022	1,000,000,000Jpy
Sales record	14 equipment

○Sales equipment type

RtoR Connecter Plating Equipment
Full Auto Wafer Plating System
Semi Auto Wafer Plating System
Lead frame Plating Equipment Cut Sheet or RtoR
PCB Plating Equipment、
Plating Tool (Silicon mask etc)

Introduction of UI SCIENCE

Concept of Equipment

- **We are familiar with the latest plating equipment technology.**
  State-of-the-art equipment group.

- **Our equipment was designed for high spec ideas.**
  This is a custom-made Equipment for which you can request specifications.

Organizational Structure

Officer Sales
Accounting, general affairs
Technical design
Production control
Production
System Control

Introduction of Plating equipment.

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Full Auto Wafer Plating System

Model : FAWPS-04～08

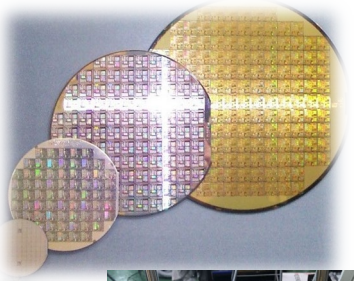
Chamber : 4～8 Chamber

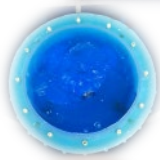
Through put : MAX 10000wafer/month

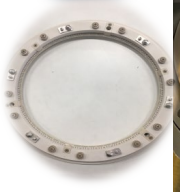
Wafer size :φ75-φ100-φ125-φ150-φ200
3inch-4inch-5inch-6inch-8inch

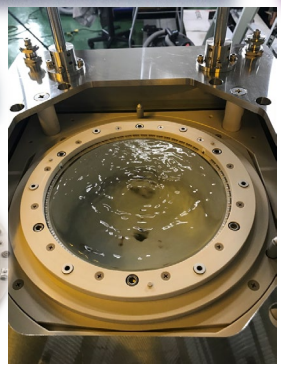
Plating spec : Cu、NI、Au、Sn etc

Wafer material :Silicon Wafer /GaAs Wafer
GaN Wafer etc









○Concept of system

- Equipped with SCARA robot for stable transportation and high quality plating .
- The two-handed SCARA robot does not stain the wafer.
- Production recipe, production record, production recording function installed (compliant with SECS standard)
- High quality plating supported by original face down Chamber
- Supports high-quality plating by installing wafer contact ring cleaning function

(Model 2018 φ200-8chamber-4SRD)

Introduction of Plating equipment.

Semi Auto Wafer Plating System

Model : SAWPS-04～14

Chamber : 4～14 Chamber

Through put : MAX 10000wafer/month

Wafer size :φ75-φ100-φ125-φ150-φ200
3inch-4inch-5inch-6inch-8inch

Plating spec : Cu、NI、Au、Sn etc

Wafer material :Silicon Wafer /GaAs Wafer
GaN Wafer etc

Φ200 8inch Cu 4+4+2

Φ200 8inch Cu 8+6

Introduction of Plating equipment.

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RtoR Connecter Plating Equipment

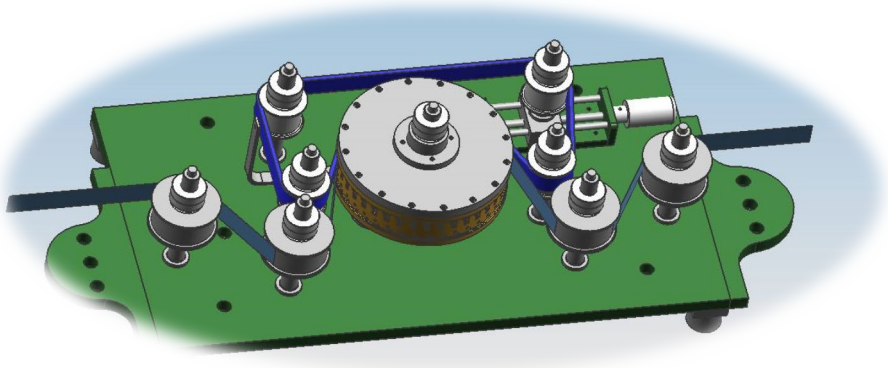
Model : UIRC-01 ～04

Number of line : 1line～4line（MAX4line）

Drive speed : 1.0～25.0m／min

Production item : Connecter、Foop
: Thickness t0.06～t1.0mm
: Hight 5～120mm

Basic plating spec :Ni＋Pd＋Au＋Sn
: Cu＋Sn＋Reflow etc
Material : Cu 、SUS etc



○Concept of Equipment

・narrow-pitch micro connector products and high quality plating support

・Automotive connector products and high quality plating support

・High-precision partial plating is possible by processing various parts plating tool

Introduction of Plating equipment.

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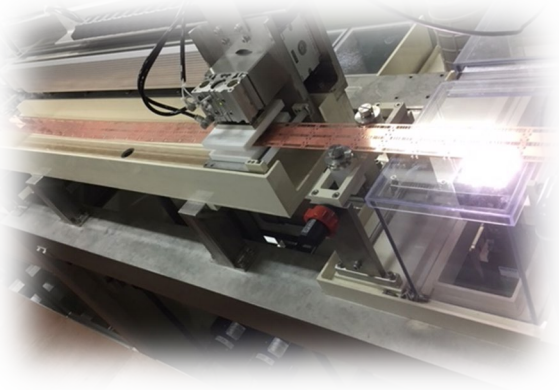
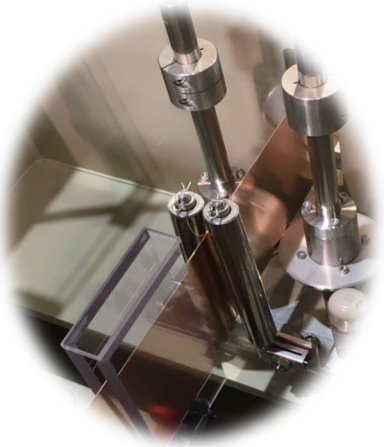
Lead frame Plating Equipment

RtoR type plating equipment



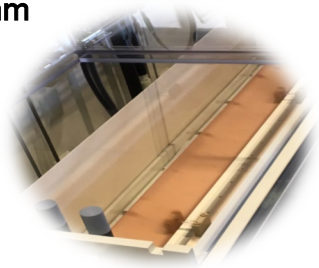


Model : UIRLF-02 ～04

Number of line : 1line～4line（MAX4line）

Drive speed : 1.0～5.0m／min

Production item : Lead frame、Foop
: Thickness t0.06～t1.0mm
: Hight 5～120mm



Basic plating spec :Ni＋Pd＋Au
: Cu＋Ag etc

Material : Cu 、SUS etc

○Concept of Equipment

・High-precision partial plating is possible by processing various parts plating tool

・Spot plating position accuracy ±0.07 mm achieved

Introduction of Plating equipment.

Lead frame Plating Equipment

Cut sheet type plating equipment

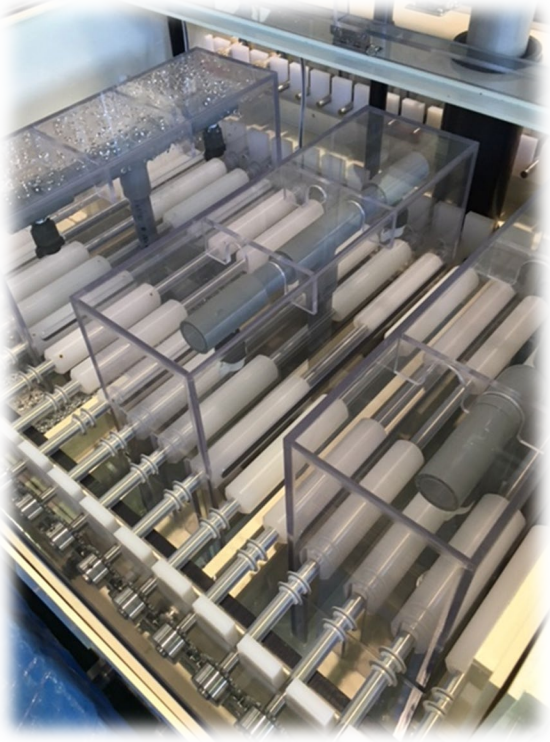
Model : UICLF-02 ～04

Number of line : 1line～4line（MAX4line）

Conveyer speed : 1.0～2.0m／min

Production item : Lead frame cut sheet
: Thickness t0.06～t0.8mm
: Wide 50～100mm

Basic plating spec :Ni＋Pd＋Au
: Cu＋Ag etc
Material : Cu 、SUS etc



○Concept of Equipment

・High-precision partial plating is possible by processing various parts plating tool

・Spot plating position accuracy ±0.05 mm achieved

Introduction of control system （ＡＤＬＳ）

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Auto Data Logging System

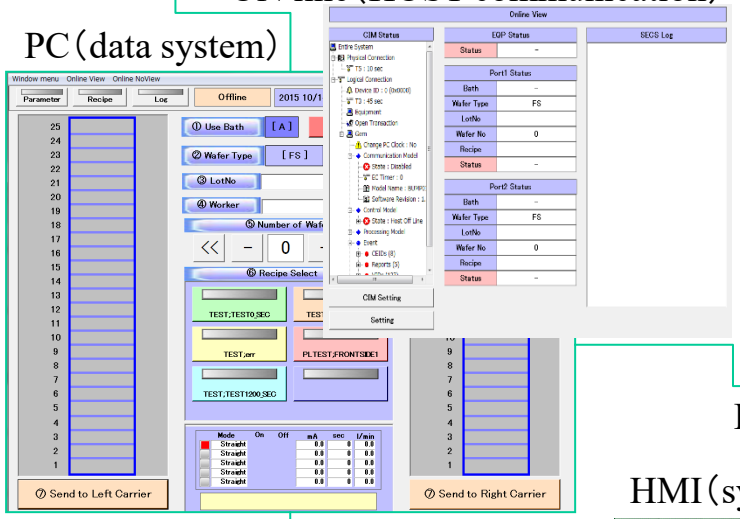
- Equipment control (Drive, robot control, etc.)
- Recipe D/L, data collection, alarm history management (PC control)
- Recipe U/L, host communication management (online control)

User HOST server

SECS/GEM

ON line（HOST communication）

PC（data system）



PLC（system Control）

Melsecnet/H

PLC（ system Control ）

…

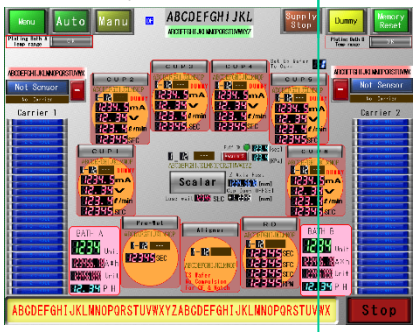
M/C Control

Ethernet

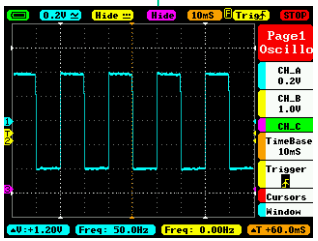
CC-Link

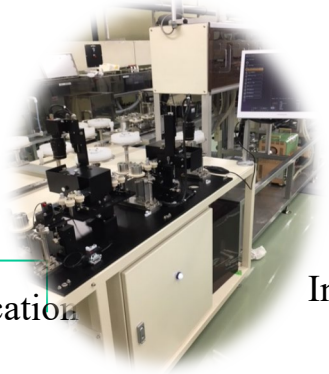
FAcom

HMI（system Control）



Ethernet





Ethernet

Inspection Control

In line record

Current control board control, jet control, etc.

RS-232Ccommunication

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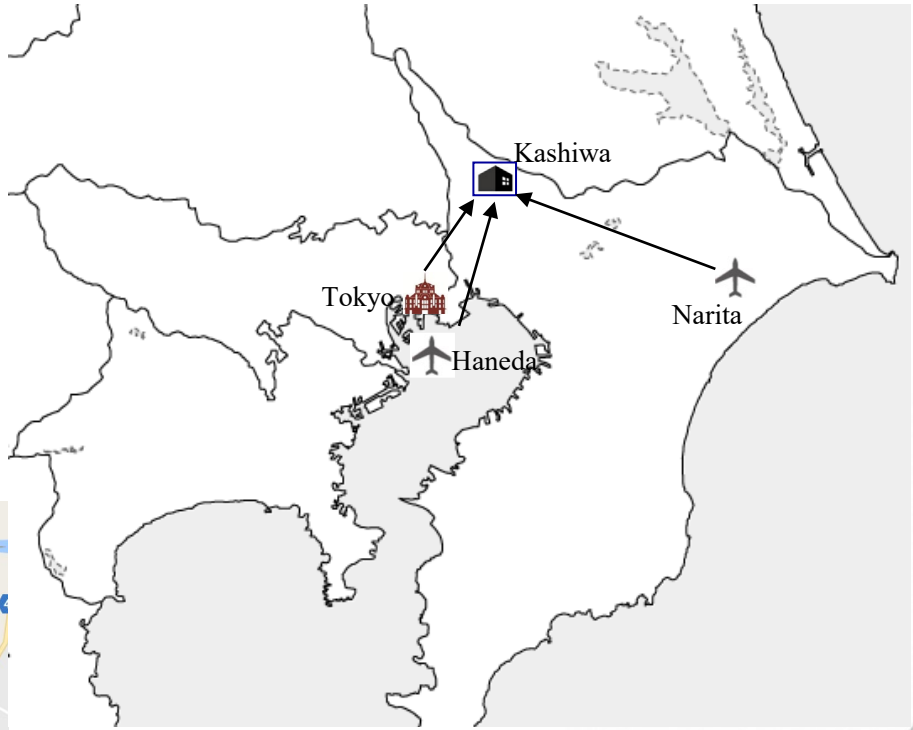
Access to UI SCIENCE

Always access to the station

35 minutes by train from Tokyo Station
60 minutes by train from Haneda Airport
75 minutes by bus
60 minutes by train from Narita Airport
90 minutes by bus



Head office factory 12m×25m
Second office factory15m×31m